

	3/6/2012		PMP7327 REVB BOM			
Qty	Ref Des	Value	Description	Size	Part Name	Manuf.
6	C13 C20 C23-24 C26 C28	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603		TDK
1	C14	100pF	Capacitor, Ceramic, 50V, COG, 15%	603		std
5	C10 C12 C19 C31 C32	1uF	Capacitor, Ceramic, 16V, X7R, 15%	603		std
1	C21	22pF	Capacitor, Ceramic, 50V, X7R, 10%	603		TDK
2	C9 C11	330pF	Capacitor, Ceramic, 50V, NPO, 5%	603		std
1	C8	0.33uF	Capacitor, Ceramic, 50V, X5R, 15%	805		TDK
1	C30	1uF	Capacitor, Ceramic, 50V, X7R, 10%	1206		TDK
6	C1-4 C6-7	10uF	Capacitor, Ceramic, 50V, X7S, 15%	1210		TDK
4	C22 C25 C27 C29	10uF	Capacitor, Ceramic, 50V, X5S, 20%	1812		Taiyo Yuden
5	C5 C15-18	1000uF	Capacitor, 50V, 3.01Arms, 20%	16x25mm	50VZL1000uF20%16X25	Rubycon
1	D1	BAT54HT1	Diode, Schottky, 200mA, 30V	SOD323	BAT54HT1	On Semi
1	D2	MBR30L45CTG	Diode, Dual Schottky 30A, 45V	TO220	MBR30L45CTG	On Semi
1	D3	10V	Diode, Zener, 10V	SOD123	MMSZ5240BT1	On Semi
1	D4	6.2V	Diode, Zener, 6.2V	SOD123	MMSZ5234BT1	On Semi
2	D6 D7	Green	Diode, LED, Green, 2.1V, 20mA, 6mcd	603	LTST-C190GKT	Lite On
1	L2	6.8uH	Inductor, SMT, 6.64A, 12.3 milliohm	12.5 x12.5mm	DR125-6R8-R	Cooper
1	L1	6.8uH	Inductor, 45.9A, 2.6 milliohm	1.1" x 1.1"	SER2918H-682KL	Coilcraft
1	R22	49.9	Resistor, Chip, 1/16W, 5%	402	STD	STD
1	R20	100	Resistor, Chip, 1/16W, 1%	402	STD	STD
2	R11 R13	10K	Resistor, Chip, 1/16W, 1%	402	STD	STD
3	R7 R25 R27	0	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R30	4.7	Resistor, Chip, 1/16W, 1%	603	STD	STD
2	R1 R26	10	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R17	49.9	Resistor, Chip, 1/16W, 1%	603	STD	STD
2	R14 R15	100K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R10	1K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R18	2.74K	Resistor, Chip, 1/16W, 1%	603	STD	STD
5	R3 R8-9 R23 R24	20K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R4	22.1K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R6	261K	Resistor, Chip, 1/16W, 1%	603	STD	STD
1	R21	100K	Resistor, Chip, 1/10W, 1%	805	STD	STD
1	R16	82.5K	Resistor, Chip, 1/10W, 1%	805	STD	STD
1	R5	909K	Resistor, Chip, 1/10W, 1%	805	STD	STD
1	R29	10	Resistor, Metal Film, 1/4 watt, 5%	1206	STD	STD
1	R19	0.01	Resistor, Chip, 1/2W, 1%	2010	STD	STD
2	R2 R12	0.005	Resistor, 1W, 5%	2512	STD	STD
1	Q2	MMBT3904LT1G	Trans, NPN, 40V, 200mA, 225mW	SOT23	MMBT3904LT1G	On Semi
2	Q1 Q4	SiR426DP	MOSFET, NChan, 40V, 30A, 12.5 milliohm	PWRPAK S0-8	SiR426DP	Vishay
1	Q5	SiR414DP	MOSFET, NCh, 40V, 50A, 2.8 milliohm	PWRPAK S0-8	SiR414DP	Vishay
1	U1	TPS40210DGQ	IC, 52V, Current Mode Boost Controller	DGQ10	TPS40210DGQ	TI
1	U2	UCC27324D	IC, Dual 4A High Speed MOSFET Driver	SO8	UCC27324D	TI
1	U3	BQ24640RVA	IC, 28V Super Cap Charger	QFN	BQ24640RVA	TI
<b>MISC</b>						

2	J1 J3	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27" x 0.25"		OST
1	J2	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
2	J4-5	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27" x 0.25"	ED555/2DS	OST
4	TP3 TP4 TP8 TP19	5000	Test Point, Red, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
2	TP7 TP18	5000	Test Point, Red, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
3	TP11 TP14 TP17	GND	Test Point, Black, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
2	TP9-10	5002	Test Point, White, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
1	TP21	STAT	Test Point, White, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
2	TP13 TP16	VCC	Test Point, White, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
2	TP15 TP20	~PG	Test Point, White, Thru Hole Color Keyed	0.1" x 0.1"		Keystone
2	TP1 TP5	5010	Test Point, Red, Thru Hole	0.125"x 0.125"		Keystone
3	TP2 TP6 TP12	5011	Test Point, Black, Thru Hole	0.125"x 0.125"		Keystone

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